Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-07-12
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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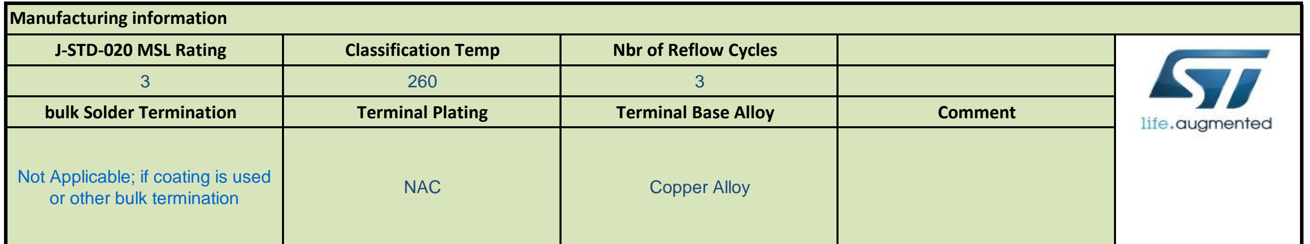
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H747AII6	P0OQ*450XXXV	A	9996	2018-07-12
	Amount	UoM	Unit type	ST ECOPACK Grade
	58.50	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	7x7x0.6	235	No lead	
Comment	Package : A0YV UFBGA 7X7X0.6 169L P 0.5 MM 8502430			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**TRUE**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :
note : Substance present with less 0.001mg will not be declared in this document

						Mfr Item Name	P0OQ*450XXXV				6000000.0	1000000.0
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	4.802	mg	supplier	die	Silicon (Si)	7440-21-3		4.060	mg	845481	69402
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	18326	1504
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	57476	4718
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	208	17
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	9371	769
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	1666	137
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	208	17
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	67264	5521
SUBSTRATE (DS7409HGB)	M-011 Other inorganic materials	33.060	mg	supplier	CORE	Glass Cloth	65997-17-3		1.176	mg	35580	20107
				supplier	CORE	Copper (Cu)	7440-50-8		2.941	mg	88950	50268
				supplier	CORE	Epoxy	28906-96-9		0.412	mg	12453	7038
				supplier	CORE	Flame resistant resin	223769-10-6		0.294	mg	8895	5027
				supplier	CORE	Heat resistant resin	25722-66-1		0.294	mg	8895	5027
				supplier	CORE	Silica filler	7631-86-9		0.529	mg	16011	9048
				supplier	CORE	Metal Hydroxide	Proprietary		0.235	mg	7116	4021
				supplier	SOLDERMASK (AUS320)	Solvent naphtha (petroleum), Heavy arom.	64742-94-5		1.142	mg	34550	19525
				supplier	SOLDERMASK (AUS320)	Naphthalene	91-20-3		0.120	mg	3643	2059
				supplier	SOLDERMASK (AUS320)	Phosphinoxide derivative	Proprietary		0.042	mg	1256	710
				supplier	SOLDERMASK (AUS320)	Talc containiing no asbestiform fibers	14807-96-6		0.312	mg	9423	5325
				supplier	SOLDERMASK (AUS320)	Barium sulfate	7727-43-7		0.519	mg	15704	8875
				supplier	SOLDERMASK (AUS320)	Dipropylene glycol monomethyl ether	34590-94-8		0.312	mg	9423	5325
				supplier	CU FOIL	Copper (Cu)	7440-50-8		14.328	mg	433400	244926
				supplier	NI PLATING	Nickel (Ni)	7440-02-0		8.550	mg	258621	146154
				supplier	AU PLATING	Gold (Au)	7440-57-5		1.854	mg	56080	31692
DIE ATTACH (ATB-130U)	M-011 Other inorganic materials	0.443	mg	supplier	GLUE	Butadiene,acrylonitrile polymer,carboxy-termi	68610-41-3		0.266	mg	600000	4544
				supplier	GLUE	Phenol-formaldehyde polymer	9003-35-4		0.044	mg	100000	757
				supplier	GLUE	Phenol polymer with formaldehyde,glycidyl et	28064-14-4		0.044	mg	100000	757
				supplier	GLUE	Dapsone	80-08-0		0.044	mg	100000	757
				supplier	GLUE	Reaction product bisphenol-A-(epichlorhydrin	25068-38-6		0.004	mg	10000	76
				supplier	GLUE	4,4, Isopropylidenediphenol	80-05-7		0.004	mg	10000	76
				supplier	GLUE	Other Substance	Proprietary		0.035	mg	80000	606
BONDING WIRE (Au wire)	M-011 Other inorganic materials	1.404	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		1.404	mg	1000000	23995
SOLDERBALL (Sn96.5Ag3.5)	M-011 Other inorganic materials	5.248	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		5.169	mg	985000	88359
SOLDERBALL (SAC 105)			mg	supplier	SOLDERBALL	Copper (Cu)	7440-50-8		0.079	mg	15000	1346
ENCAPSULATION (GE-100LFCS)	M-011 Other inorganic materials	13.544	mg	supplier	MOLDING COMPOUND	Silica vitreous	60676-86-0		11.923	mg	885000	203812
				supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		0.564	mg	40000	9636
				supplier	MOLDING COMPOUND	Phenol resin	Proprietary		0.423	mg	30000	7227
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4		0.070	mg	5000	1204
				supplier	MOLDING COMPOUND	Metal hydroxide	Proprietary		0.423	mg	30000	7227
				supplier	MOLDING COMPOUND	Crystalline silica	14808-60-7		0.141	mg	10000	2409